

Solder Paste "for MYDATA Jet Printers"

Completely compatible with stencil-free printer MY500. Increased quality control through steady printing and exceptional melting techniques.

MDA-5

Sn-Ag-Cu solders

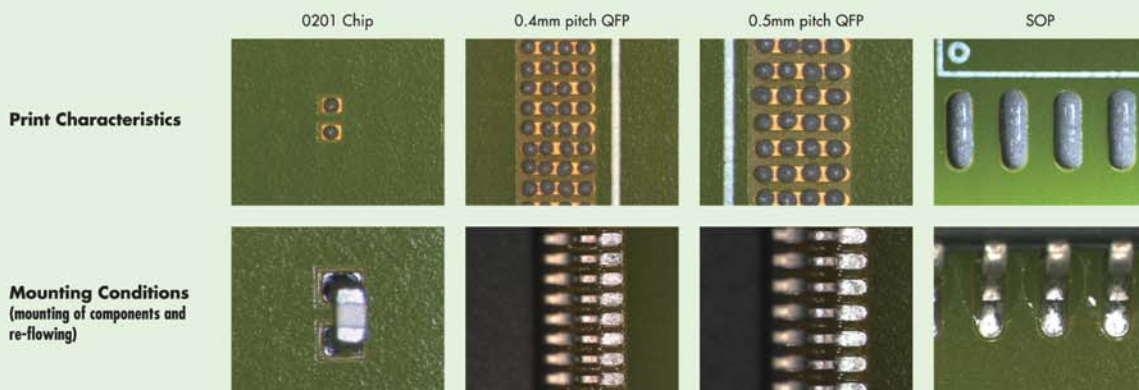
1. A constant supply for your printing needs, from small to large deposit.
2. Prevents de-wetting, solder balls, and voids on the smallest scale.
3. Reliability of flux is high enough for the product to be used without cleaning.
4. Exceptional efficiency with the on-demand properties of MYDATA's MY500 series of printers.
5. Useable with a large range of reflow profiles.

Examples of application : For printing small quantities of highly diverse circuit boards.



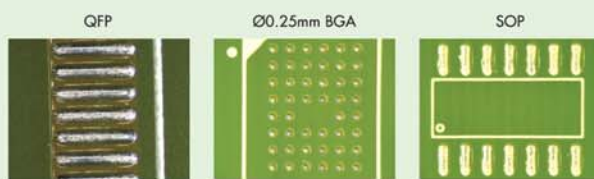
Check of the printing and mounting characteristics

[Condition] Solder is printed onto each test circuit board with the MY500. A check of the mounting condition is then performed.



Test of wetting properties

[Condition] Print test using MY500 on circuit boards. Mount components and reflow. Check of the mounted soldering state.



SS4M Leaded Solder

Solder with Lead content was tested at the same condition as the above MDA-5 flux.

Product name component for solder paste

(Example) LFM-14 U MDA-5
Alloy type; powder size; flux name

Solder paste products specification

Flux name	Alloy type	Powder size	Flux content	Viscosity	Melting point temperature
MDA-5	LFM-14 (Sn-3.5Ag-0.7Cu)	U	15.0%	90Pa · s	217-220°C
SS4M	Sn62 (Sn-Pb-2Ag)	U	15.0%	100Pa · s	179-190°C

*LFM-14 has been sublicensed for JP PAT No. 3027441 and US PAT No. 5527628. *100g syringe is standard. *Powder size is U: 10~28µm.
*When your ordered product is out of stock, please contact our sales representative.